**Amendments to the Specification:**

Please replace the paragraph beginning at page 9, line 20, with the following amended paragraph:

-- Referring to FIG. 4, in a second aspect of this preferred embodiment the wall 40 of the environmental enclosure ~~40~~ 2 is extended to substantially surround the thermal devices 42, the thermal device shell 44 and the power cable 46, comprising electrical conductors 43, connecting the thermal devices 42 to the thermal driver controller 50. Heat is transferred to and from the device supporting surface 56 of the chuck ~~56~~ 70 through the thermal device shell 44 and the wall of the environmental enclosure 40, which includes an outer surface 40B and inner surface 40A enclosing the chuck and having a portion 40C that separates the device supporting surface of the chuck from the thermal devices 42. The thermal devices 42 are capacitively coupled to the thermal shell 44 by virtual capacitors 48. The thermal device shell 44 and the shield of the power cable 46 are, in turn, capacitively coupled to the wall of the environmental enclosure 40 by virtual coupling capacitors 52. Capacitive currents in the thermal device shell 44 or the shield of the cable 46 are returned to the thermal driver controller 50 through the conductive shield layer of the cable 46. The thermal driver controller 50 is connected to the thermal devices 42 by power conductors 43 and to ground at ground 51. Capacitive currents leaking from the thermal device shell 44 or the power cable 46 will be intercepted by the wall of the enclosure ~~40~~ and returned to the enclosure ground 54 when the switch 53 is closed. When the switch 53 is open, capacitive currents in the wall 40 of the environmental enclosure ~~40~~ are returned to the ground 55 of the instrument 57. The instrument 57 is connected to the probes 6 inside the environmental enclosure by instrument leads 47. --

Please replace the paragraph beginning at page 10, line 10, with the following amended paragraph:

-- Referring to FIG.5, in a third aspect of this preferred embodiment the wall 60 of the environmental enclosure ~~60,~~ 2, comprising an inner surface 60A defining the interior of the enclosure and an outer surface 60B, is extended to substantially surround the thermal devices 64 and the power conductors 62 connecting the thermal devices 64 to the thermal driver controller 63. The outer surface 60B of the wall 60 substantially encircles the thermal

devices 64 so that portion of the wall including a portion 60C of the inner surface 60A separates the thermal devices from the device supporting surface 56 of the chuck 70. The thermal driver controller is grounded at ground 74. In this aspect of the invention, the thermal devices 64 and the power conductors 62 are capacitively coupled to the wall 60 of the environmental enclosure ~~60~~ through the virtual coupling capacitors 66. Capacitive currents generated in the thermal devices 64 or power cables 62 are intercepted by the shield formed by the conductive wall of the enclosure 60 and returned to the enclosure ground 68 when the switch 69 is closed. If the switch 69 is open the walls of the enclosure ~~60~~ are grounded through the instrument 73 to the instrument ground 71. Heat is transferred to and from the chuck 70 through the wall 60 of the environmental enclosure ~~60~~. --